

ABSTRACT OF THE DISCLOSURE

An adaptable semiconductor chip cooling system having a readily openable enclosure defining a chamber configured to hold a printed circuit board carrying components to be cooled. Within the enclosure is a sprayer delivery system with a height-controllable sprayer for spraying hot components. The sprayer delivery system has an actuator configured to move the sprayer among positions for spraying different components. The actuator can be of the types used for ink-jet printers or X-Y plotters. Alternatively, the actuator can be a continuous ribbon loop, or a series of radially extending rails. The actuator and sprayer are controlled by a controller, which also controls a configuration system that configures the sprayer delivery system for use with different boards. The controller uses sensors that sense the temperature of the hot components.